


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[STACK-TYPE MULTI-CHIP PACKAGE AND METHOD OF FABRICATING BUMPS ON THE BACKSIDE OF A CHIP]	
Application Type : regular, utility Attorney Docket Number : 10544-US-PA		
Correspondence address: Customer Number: 31561 		
Priority Data: Doc.No: 92109018; Country -TW ; Date: 2003-04-18 us-priority-claimed		
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Chih-Huang Family Name: Chang Residence: City of Residence: Tainan Hsien Country of Residence: TW Address-1 of Mailing Address: No. 11, Lane 158, Hsishih Rd., Yungkang City, Address-2 of Mailing Address: City of Mailing Address: Tainan Hsien State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor		

Citizenship: TW
Name prefix: Mr.
Given Name: Shau-Chuo
Family Name: Wen
Residence:
City of Residence: Kaohsiung
Country of Residence: TW
Address-1 of Mailing Address: No. 9, Lane 190, Ruei-Chu Rd., Fengshan,
Address-2 of Mailing Address:
City of Mailing Address: Kaohsiung Hsien
State of Mailing Address:
Postal Code of Mailing Address:
Country of Mailing Address: TW
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.